Fundamentals of CMOS Design II

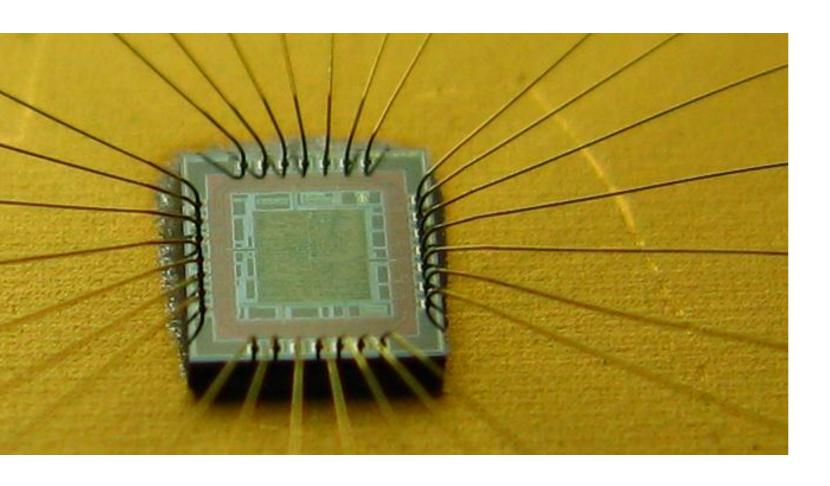
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Outline

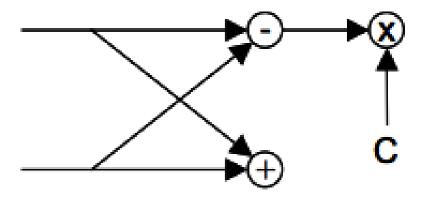
Gate Performance
Gate Power
System Analysis

Gate Performance

We want to build Chips

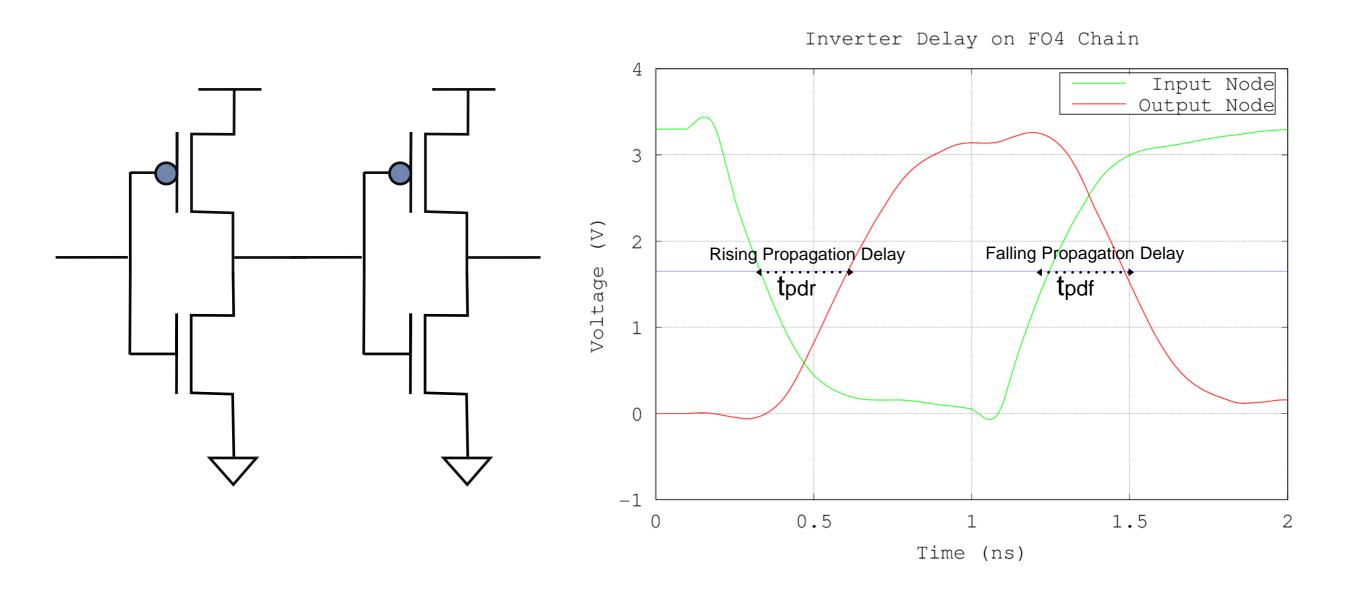


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To perform complex binary calculations

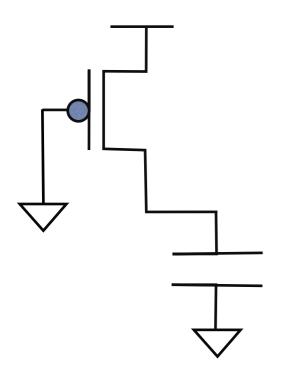
But what we are really are building **CIRCUITS**

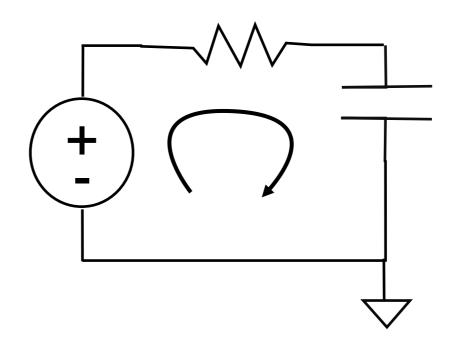


And circuits have transient response

Pull Up Delay

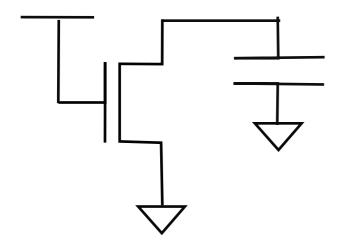
Rise time calculation

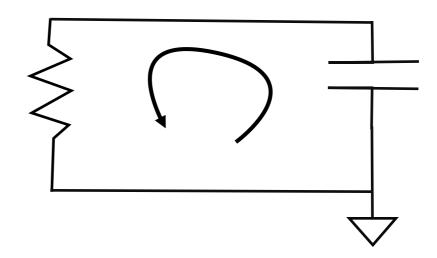




Pull Down Delay

Fall time calculation

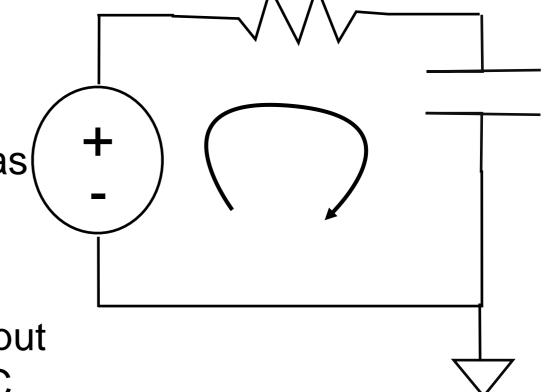




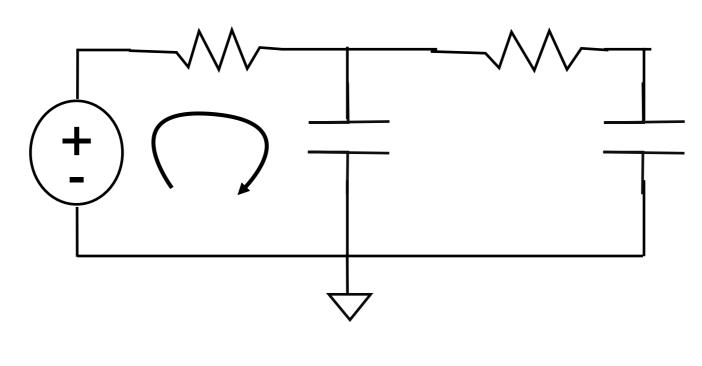
Delay - And then...

$$H(s) = \frac{1}{1 + sRC} \qquad \Rightarrow \qquad V_{out} = V_{dd}(1 - e^{\frac{-t}{R_PC}})$$

- Propagation delay is the time when when Vout reaches ½ Vdd
- $t_{pd} = RC * ln2 = 0.69 * RC$
- So simple that we will take this value as the delay for hand calculations.
- Define gate delay as: Time from input crossing Vdd/2 to output crossing Vdd/2 and approximate to RC



Unfortunately, we don't always have a 1st order system

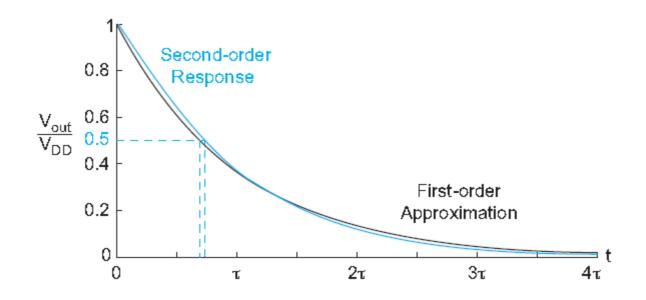


$$H(s) = \frac{1}{1 + s(R_1C_1 + (R_1 + R_2)C_2) + s^2R_1C_1R_2C_2}$$

This is too complex. It defeats the purpose of simplifying a CMOS circuit into an equivalent RC network

Need something simpler!

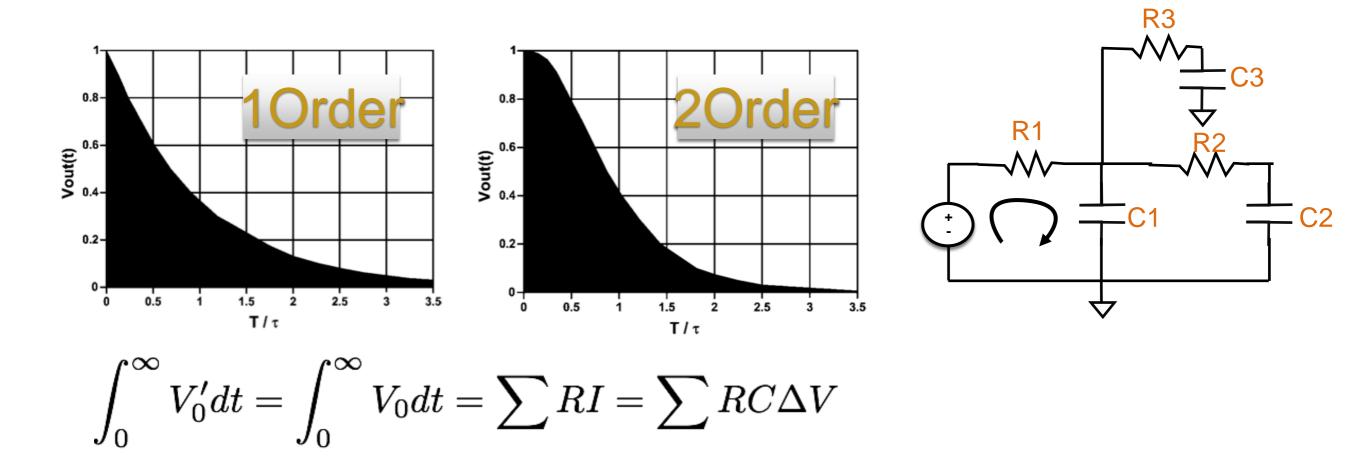
Sometimes we can approximate the response considering just the dominant pole



- This works very well when the time constant of the dominant pole is much bigger than the other (error < 7%)
- Worst case (when time constants are equal) has error < 15%
- The problem here is that this approximation doesn't describe well intermediate nodes

Elmore Delay

- This approximation is based on finding an equivalent 1st order reponse for the actual response of our circuit
- To find an equivalent τ we match the area under the step response curve of our circuit to the area of a 1st-order response

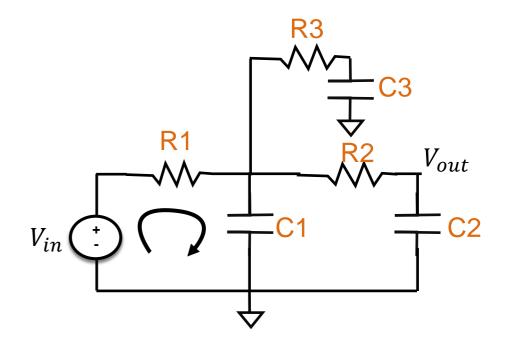


Elmore Delay

The Elmore time constant τ_E is the sum over each node in the ladder of the resistance R_{n-1} between that node and the source V_{in} , multiplied by the capacitance on the node C_i

$$t_{pd} = \tau_E * ln2$$

In this example, the τ_D at V_{out} is calculated as



$$\tau_D = R_1 C_1 + (R_1 + R_2) C_2 + R_1 C_3$$

Note that R_3 is dropped because it is not in the signal path (C_3 gets connected directly to the node)

Delay - Can we make this assumption?

Conductor Resistance:

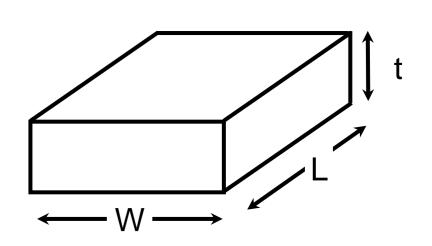
$$R = \frac{\rho L}{tW}$$

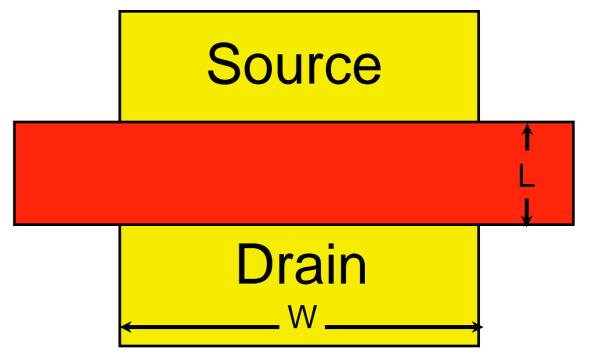




- Actually I_{ds}^-1
- ▶ Prop^-1 to Vdd.
- Approximated by:

$$R \approx \frac{L}{W} K_{technology}$$

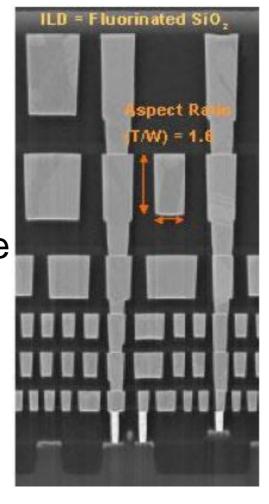


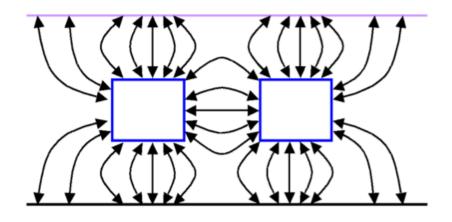


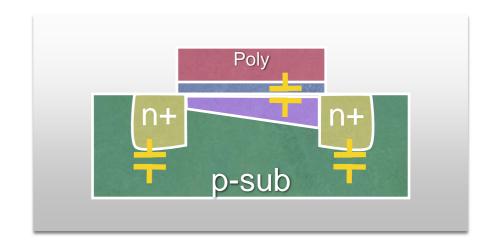
Delay - Capacitance

C_{load} comes mainly from three factors:

- 1. Gate capacitance of driven transistors.
- 2. Diffusion capacitance (due depletion region) of source/drain connected to the wire.
- 3. Wire capacitance.

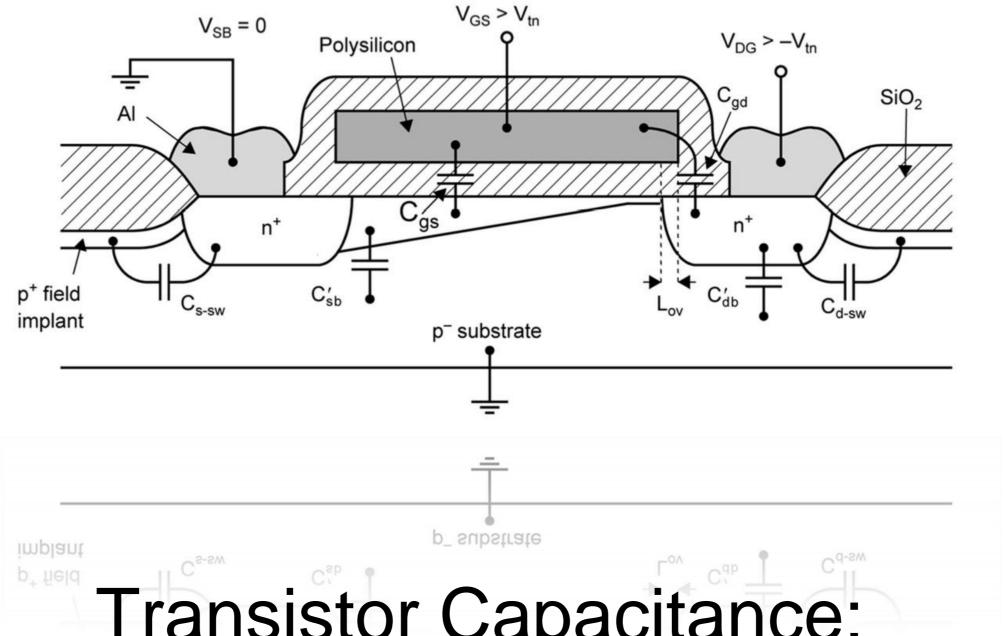






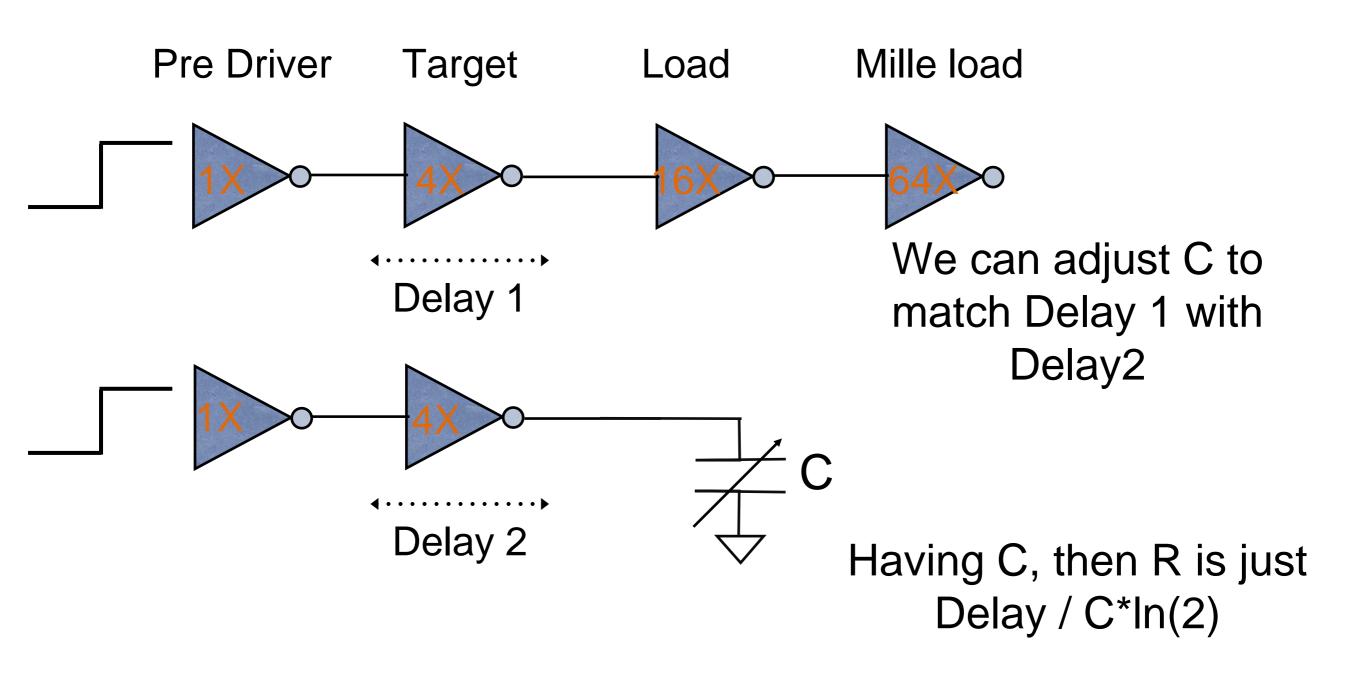
$$C_g = C_{ox}WL = C_{permicron}W$$
,

$$C_{ox} = \frac{\varepsilon_{ox}}{t_{ox}}$$

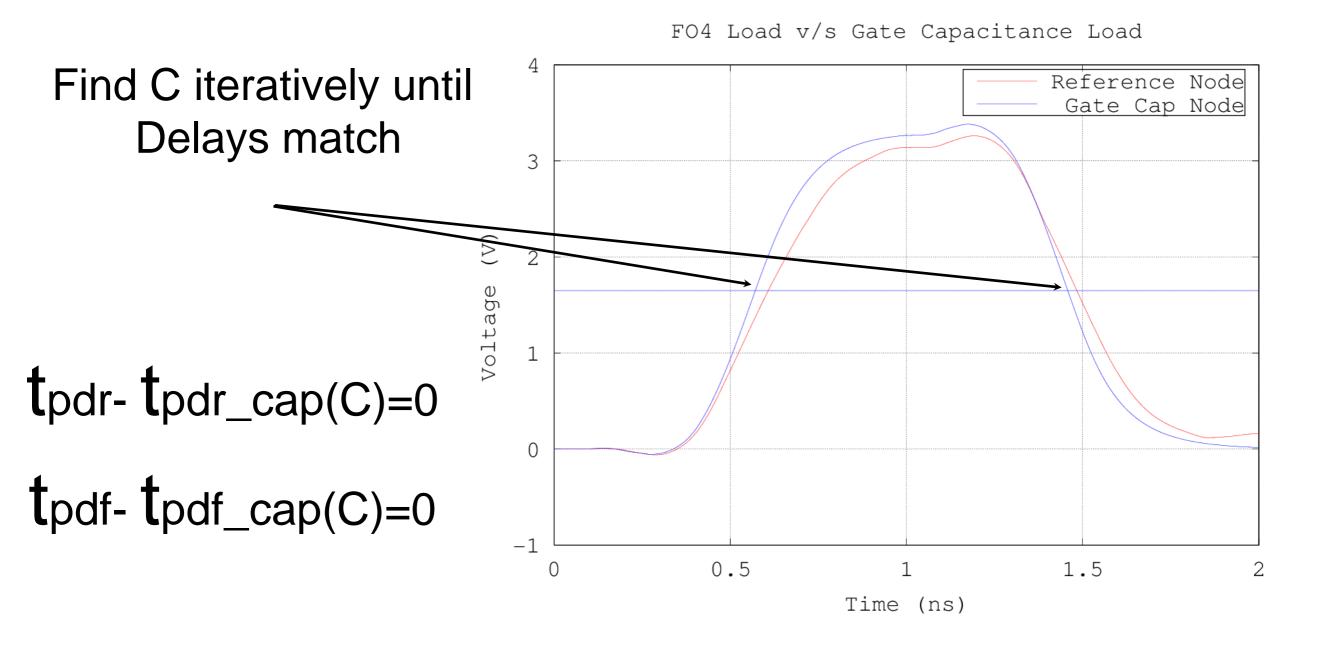


Transistor Capacitance: Many Sources

+ Process Calibration



+ Process Calibration



Example

octave:1> source calib_opt.m

supply = 3.3000

 $cload_rise = 8.9632e-13$

 $cload_fall = 7.6845e-13$

cload = 8.3238e-13

WNDIFF_rise = 0.0015621

WNDIFF_fall = 0.0017749

WNDIFF = 0.0016685

delay = 2.6400e-10

cg = 1.4451e-15

Cdiff = 4.9887e-16

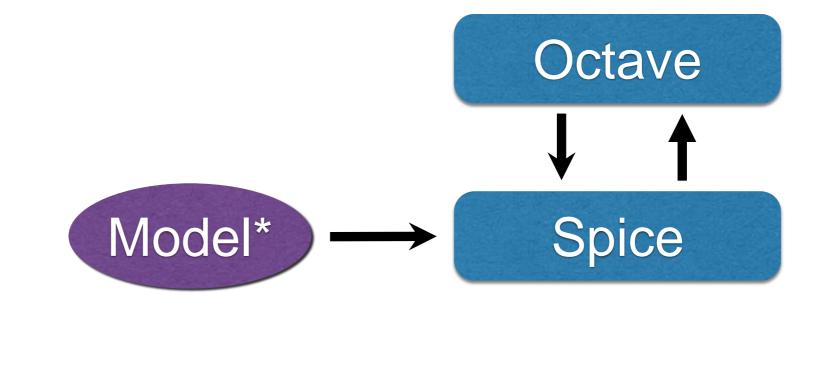
gamma = 0.23014

RN = 7321.1

RP = 1.4642e + 04

Rsq = 3.6605e + 04

Cg = 1.445110 fF/um, Cd = 0.498875 fF/um Rsq = 36.605 kOhm/sq

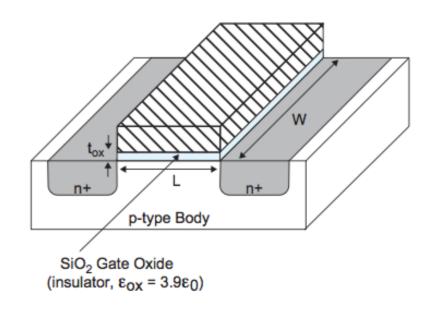


Process	Cgate	Cdiff	Rsq
0.5 um Pr05ocess	1.445 fF/um	0.499 fF/um	36.6 KOhm

^{*} http://www.mosis.com/files/test_data/ami_c5n_corner_bsim3.txt

Current in a MOSFET

$$I_{ds} = \frac{1}{2}\mu C_{ox} \frac{W}{L} (V_{gs} - V_t)^2$$



^{*} Read Weste/Harris Ch3 for a complete derivation. Notice this is not even close to current in a real transistor.

Gate Power

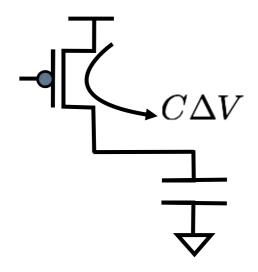
What about Power?

- Well, Power = Energy / time
- And takes energy to move charges to a voltage source

$$E = Q [cb] * V [J/cb]$$

Now to drive a gate we need C*ΔV charges:

$$E = C V^2$$



$$E_{source} = \int_0^{Tc} i_{dd} V_{dd} dt = V_{dd} C_{load} \int_0^{Tc} \frac{dV_{dd}}{dt} dt = V_{dd} C_{load} \int_0^{V_{dd}} dV = C_{load} V_{dd}^2$$

$$E_C = \int_0^{Tc} i_C V_C dt = C \int_0^{Tc} V_C \frac{dV_C}{dt} dt = C_{load} \int_0^{V_{dd}} V_C dV = \frac{1}{2} C_{load} V_{dd}^2$$

$$E_{disipated} = E_{source} - E_C = \frac{1}{2}C_{load}V_{dd}^{2}$$

Dynamic Power

Now we know each transition dissipates some Energy:

$$E_{disipated} = \frac{1}{2} C_{load} V_{dd}^{2}$$

Now, think about Power. How many times will a clock line take this Energy? Over which time?

$$P_{switching} = \frac{E}{T} = \frac{Tf_{sw}(\frac{C_{load}V_{dd}^{2}}{2})}{T} = f_{sw}(\frac{C_{load}V_{dd}^{2}}{2})$$

 How many times does any signal transition per clock cycle? Let's say alpha.

$$P_{switching} = \alpha f_{sw} \left(\frac{C_{load} V_{dd}^2}{2} \right)$$

Leakage Power

- Transistor don't really shut down abruptly.
 - There is current even when Vgs < Vth
 - So cells leak current and this depend on Vth:

$$I_{leak} = I_0 e^{\frac{V_{gs-Vth}}{nV_T}}$$

$$I_0 = I_{ds_{(Vgs=Vth)}}$$

*Leakage can drop 10x for each 80mV of Vth at room to

Transition Probability

Assume

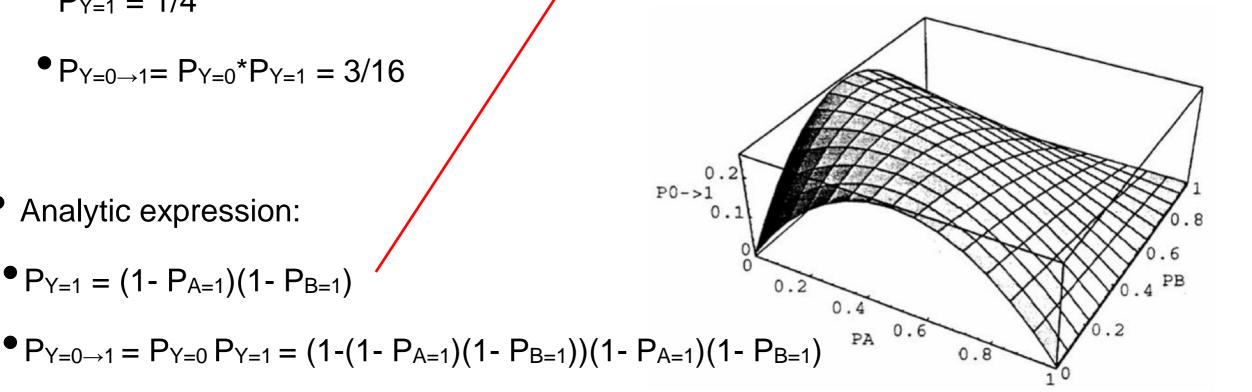
$$^{\bullet}$$
 P_{A=1}= 1/2

$$^{\bullet}$$
 P_{B=1} = 1/2

- Then:
 - $^{\bullet}$ P_{Y=1} = 1/4
 - $P_{Y=0\to 1} = P_{Y=0} P_{Y=1} = 3/16$

- Analytic expression:
- $^{\bullet}$ $P_{Y=1} = (1 P_{A=1})(1 P_{B=1})$

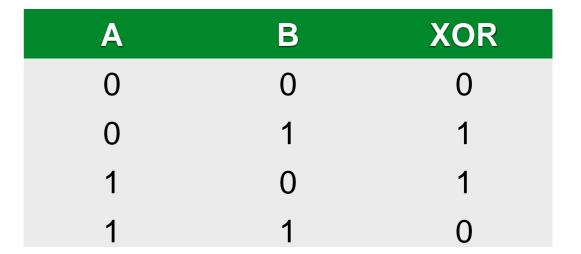
╛	Α	В	NOR	
	0	0	1	
П	0	1	0	
	1	0	0	
	1	1	0	

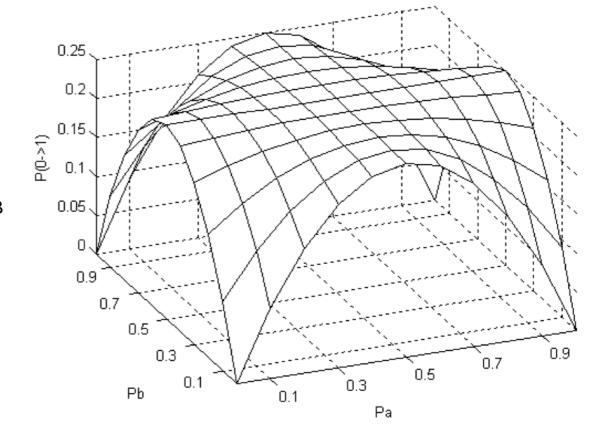


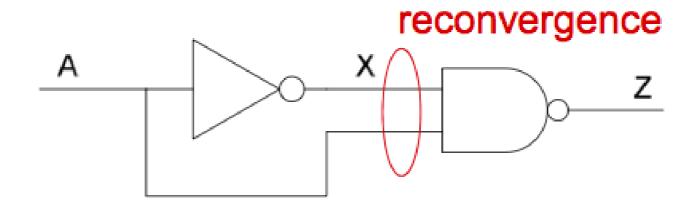
Transition Probability

- Assume
 - $^{\bullet}$ P_{A=1}= 1/2
 - $^{\bullet}$ P_{B=1} = 1/2
- Then:
 - $^{\bullet}$ P_{Y=1} = 1/2
 - $^{\bullet} P_{Y=0\to 1} = P_{Y=0} * P_{Y=1}$
 - $\alpha_{0\to 1} = 1/4$
- $^{\bullet}$ P₁ = P_A(1-P_B)+P_B(1-P_A) = P_A + P_B 2P_AP_B
- $^{\bullet}$ $P_{0\rightarrow 1}=P_0P_1$

$$=(1-P_A + P_B - 2P_AP_B)(P_A + P_B - 2P_AP_B)$$







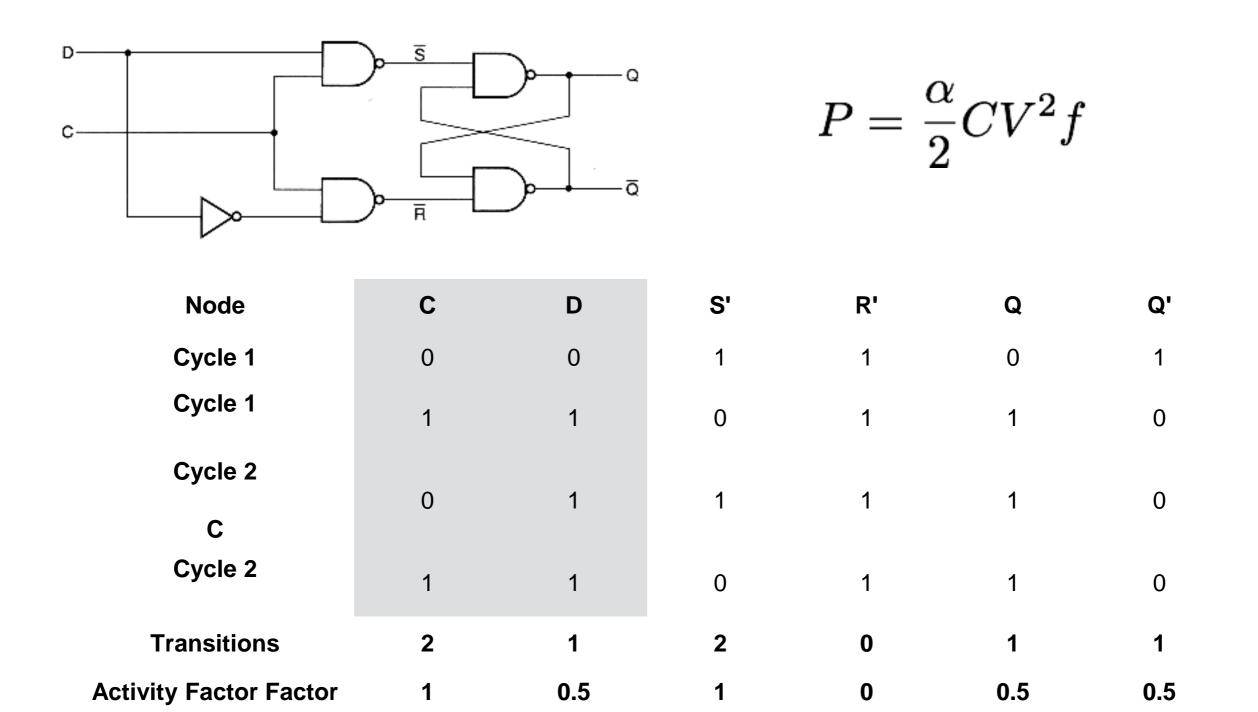
Reconvergence → Correlated inputs (NOT INDEPENDENT EVENTS)

$$P_Z = 1 - P_A^* P(X/A) = 1$$

Conditional Probability
Probability of X provided A happens first

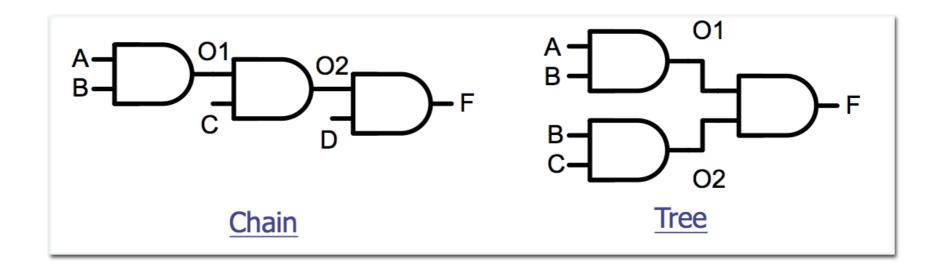
Reconvergent circuits quickly become hard to track and analyze

Power Estimation - Example



^{*} What if gates don't change instantly:

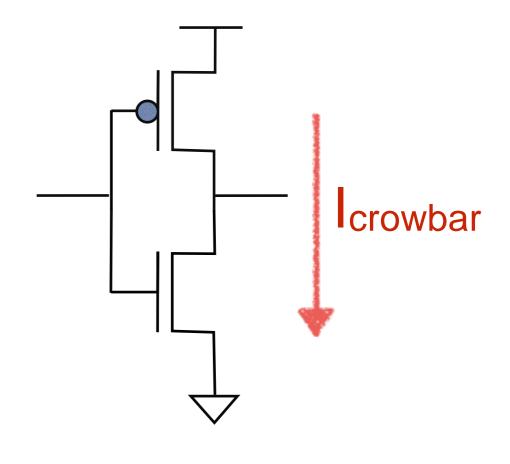
Need to consider <u>transient</u> states too (hint: glitches)



Which has higher activity factor? (more in homework)

+Crowbar current

- During circuit commutation both transistor may be active at the same time.
- On actual chips long transition time can make power dissipation to increase within 5-10% due crowbar current

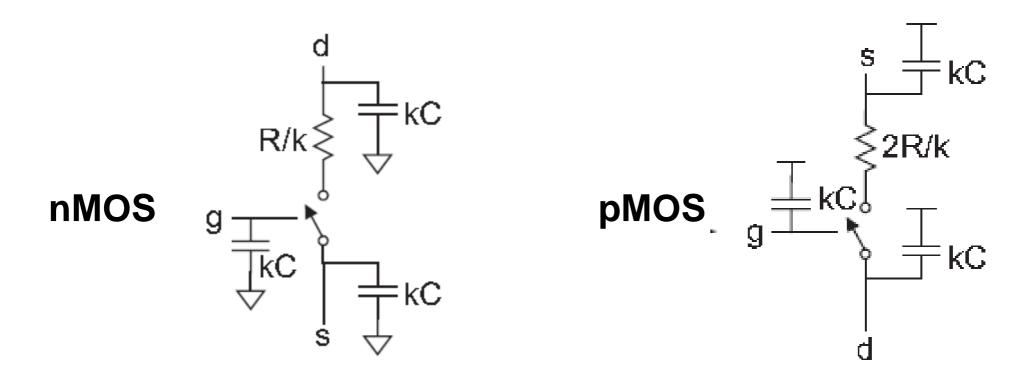


Can add this 5-10% to your hand calculations

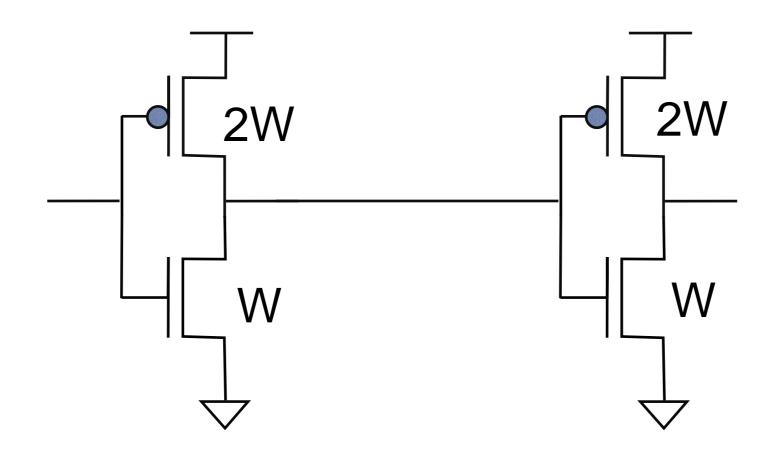
System Analysis

RC Delay model

- This model approximates the nonlinear transistor I-V and C-V characteristics with an average R and C
- Works well for delay estimation (not so well for analog behavior)
- Equivalent resistance R is the ratio Vds/lds averaged across the switching interval of interest.
- A unit nMOS transistor is defined to have a resistance of R and gate and diffusion capacitances of C
- Transistors can be modeled based on the unit transistors



Gate Performance

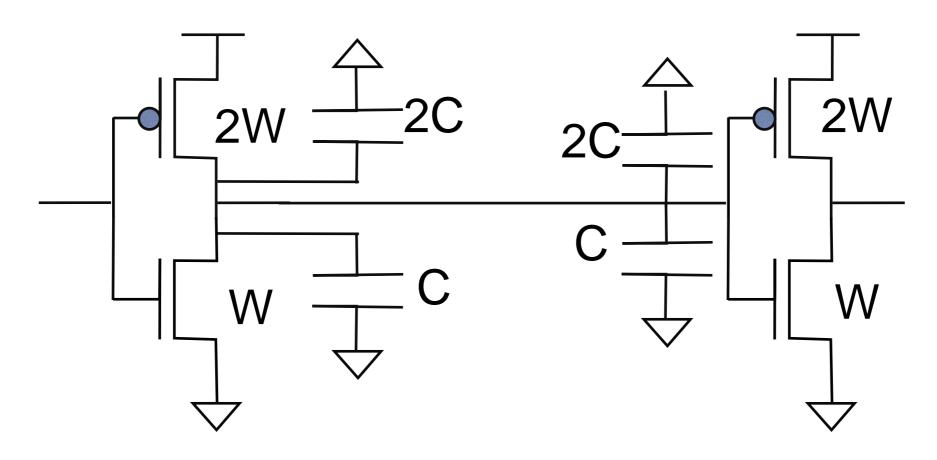


- Can you explain the transistor sizes?
- What is the value of Cload?

$$I_{DS} = \frac{\mu C_{ox} W}{L} (V_{gs} - V_t)^2$$

Gate Performance

To perform delay analysis, we need to calculate R and C!



Let's say that both Cg and Cdiff are proportional to W

$$C_g = C_{g,cons}W$$
 $C_{par} = C_{p,cons}W$

Resistance can be approximated to

$$R = \frac{W}{L} R_{sq}$$

Sizing for minimum delay

- Wider transistors reduce R $(R = \frac{L}{W}R_{sq})$, thus delay (RC) should decrease. Right?
- Wait a second... What about $C_g = C_{g,cons}W$?

Will also grow, making the previous gate slower!

Modelling inverter delay

$$t_{inv} = R_{drive}(C_{par} + C_{load})$$

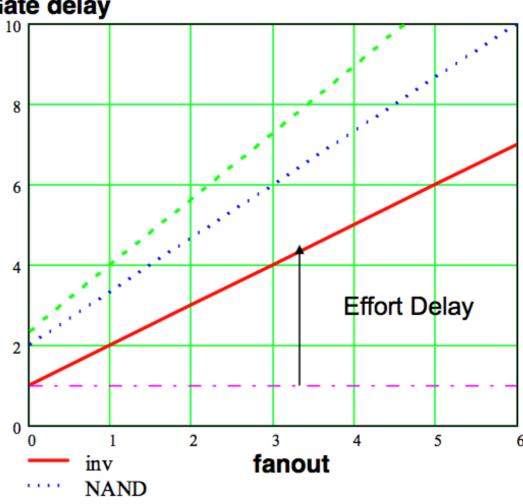
$$t_{inv} = R_{drive}(C_{par} + C_{load})$$
 $C_{in} = 3VC_{g}$ $C_{par} = \gamma C_{in} \frac{L}{R_{drive}}$ $t_{inv} = R_{drive}C_{in}(\frac{C_{par}}{C_{in}} + \frac{C_{load}}{C_{in}})_{ ext{Gate delay}}$

Some algebra and...

$$t_{inv} = 3R_{sq}C_g(\gamma + \frac{C_{load}}{C_{in}})$$

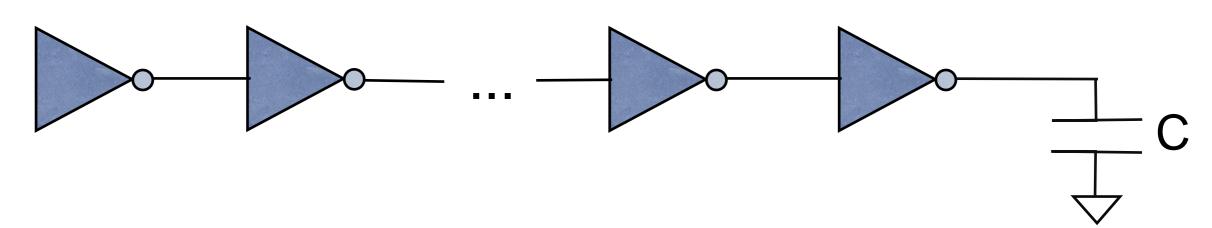
Fanout

$$C_{in} = 3WC_g$$
 $C_{par} = \gamma C_{in} \frac{L}{R_{drive}} = R_{sq} \frac{L}{W}$



parasitic

Optimizing an inverter chain



$$TotalDelay = \sum_{j=1}^{N} \tau_{inv} \left(\gamma + \frac{C_{in}^{j+1}}{C_{in}^{j}} \right)$$

$$\tau_{inv} = 3R_g C_g$$

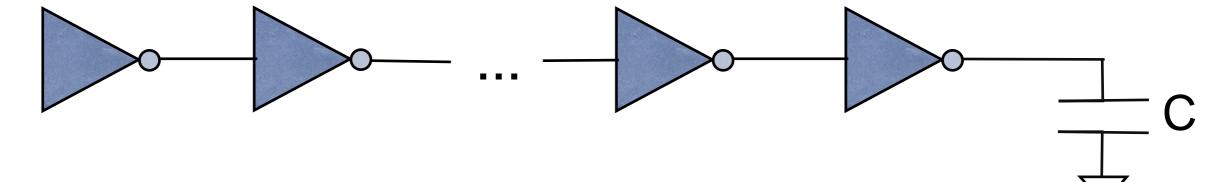
* How can we find optimum?

Optimizing an inverter chain

$$\frac{d}{dC_{in}^{j}}Delay = \tau_{inv}(\frac{1}{C_{in}^{j-1}}) - \tau_{inv}(\frac{C_{in}^{j+1}}{(C_{in}^{j})^{2}})$$

When equal to zero:

$$C_{j} = \sqrt{C^{j+1} * C^{j-1}}$$
 Or $\frac{C_{in}^{j}}{C_{in}^{j-1}} = \frac{C_{in}^{j+1}}{C_{in}^{j}}$



At the optimum, each inverter does the same effort!

If all do the same effort, how much then?

 Let's say at the optimum f is the fanout of every gate. If we multiply all the fanouts, we have

$$f = \sqrt[N]{\frac{\cancel{C2}\cancel{C3}}{C1}\cancel{C2}}...\frac{C_{N+1}}{\cancel{C_N}}$$

$$N = \frac{ln(\frac{C_{out}}{C_{in}})}{ln(f)}$$

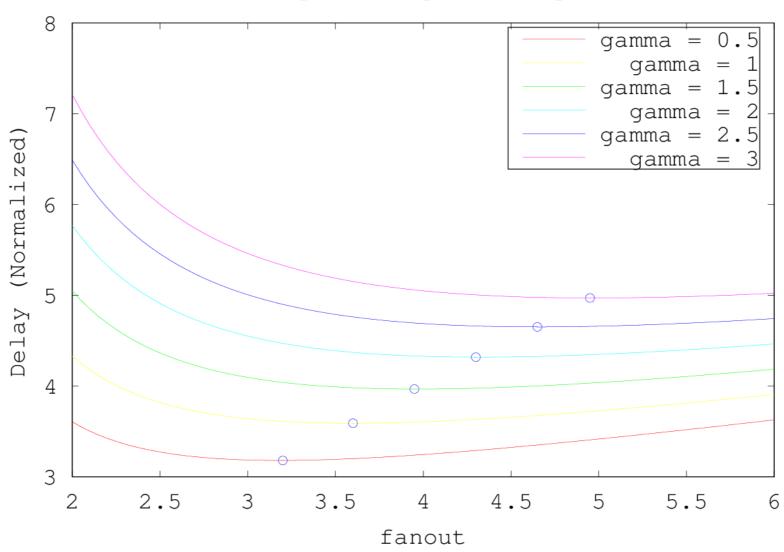
On the other hand, at the optimum we have

$$TD = \sum_{j=1}^{N} \tau_{inv} (\gamma + \frac{C_{in}^{j+1}}{C_{in}^{j}}) = N\tau_{inv} (\gamma + f)$$

$$TD = \ln\left(\frac{C_{out}}{C_{in}}\right) \tau_{inv} \frac{(\gamma + f)}{\ln(f)}$$

If all do the same effort, how much then?

Equalized path delay



To find the optimum, we derive *TD* with respect to *f*

$$TD = ln\left(\frac{C_{out}}{C_{in}}\right)\tau_{inv}\frac{(\gamma + f)}{ln(f)}$$

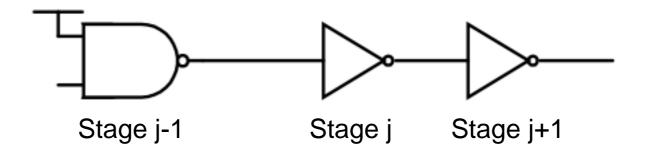
This is done graphically...

Optimum at roughly f = 4 (FO4)

But in reality...

Circuits are not made of inverters only

$$\tau_{j-1} \neq \tau_j \neq \tau_{j+1} \dots$$
$$\gamma_{j-1} \neq \gamma_j \neq \gamma_{j+1} \dots$$



At optimum

$$\tau_{nand} f_{nand} = \tau_{inv} f_{inv}$$

$$\tau_{nand} \frac{C_j}{C_{j-1}} = \tau_{inv} \frac{C_{j+1}}{C_j}$$

Note that now fanouts are not equal, they depend on τ

To optimize a heterogeneous chain, we normalize by τ_{inv}

Keep an eye on this term
$$\tau_{inv}$$
 C_j τ_{inv} C_{j-1} $=$ $\frac{\tau_{inv}}{\tau_{inv}} \frac{C_{j+1}}{C_j}$

Logical Effort

$$LE_{gate} = \frac{\tau_{gate}}{\tau_{inv}} = \frac{C_{in,gate}R_{drive,gate}}{C_{in,inv}R_{drive,gate}}$$

If we normalize the fanout ecuation at optimum, it becomes:

$$\tau_{nand} \frac{C_j}{C_{j-1}} = \tau_{inv} \frac{C_{j+1}}{C_j} \iff LE_{nand} \frac{C_j}{C_{j-1}} = LE_{inv} \frac{C_{j+1}}{C_j}$$

Note that by definition $LE_{inv} = 1$

LE of a logic gate tells how much more slowly the gate will drive a load compared to an inverter

Delay with Logical Effort

If we remember,:

$$TD = \sum_{j=1}^{N} \tau_j \left(\gamma + \frac{C_{in}^{j+1}}{C_{in}^{j}} \right)$$

Normalizing by τ_{inv} :,

$$TD_{norm} = \sum_{j=1}^{N} LE_j \left(\gamma + \frac{C_{in}^{J+1}}{C_{in}^{j}} \right)$$

Then, deriving and equaling to 0, at optimum we have

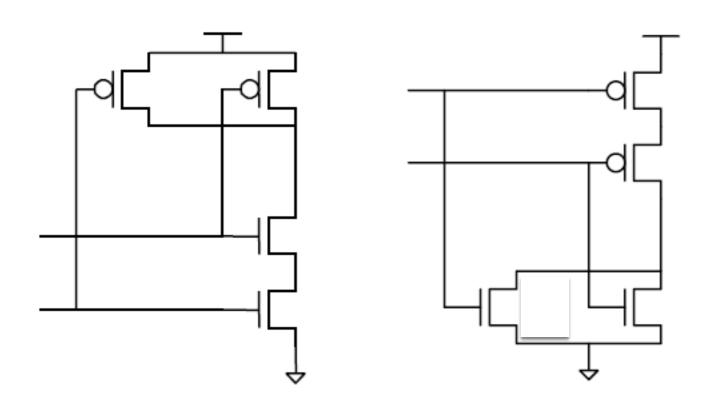
$$LE_1 \frac{C_2}{C_1} \stackrel{\leftarrow}{+} LE_2 \frac{C_3}{C_2} = \cdots = LE_{N-1} \frac{C_N}{C_{N-1}} - Stage Effort (SE)$$

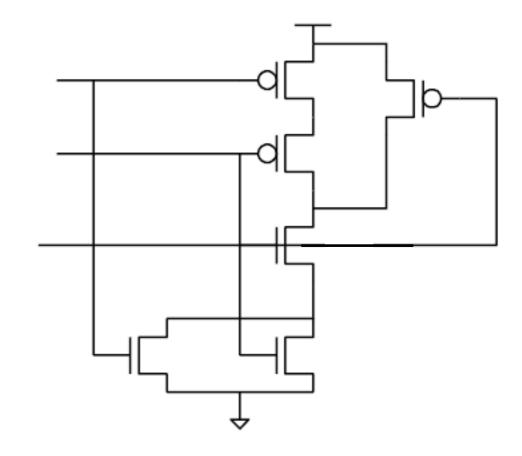
We can calculate the Effective Fanout as

Path Logical Effort (LE_{path})

$$f_{eff} = \sqrt{\frac{\sum_{j=1}^{N} LE_{j} \frac{C_{in,j+1}}{C_{in,j}}}} - \sqrt{\frac{C_{in,N_{j}}}{C_{in,1}}} LE_{j}$$
Path Fanout (f_{path})

Sizing - Example





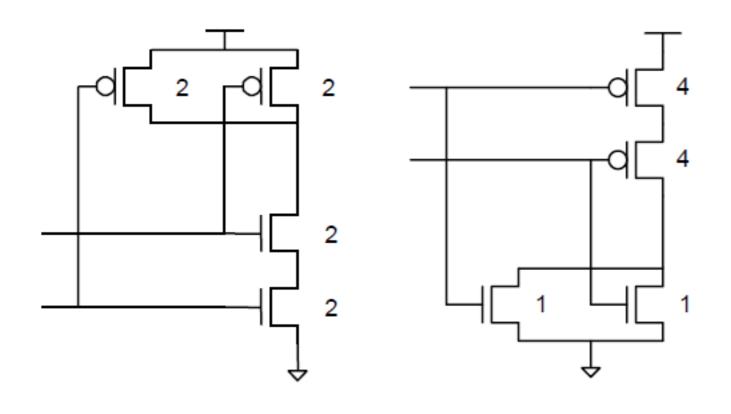
How do we size? Is LE equal for every output?

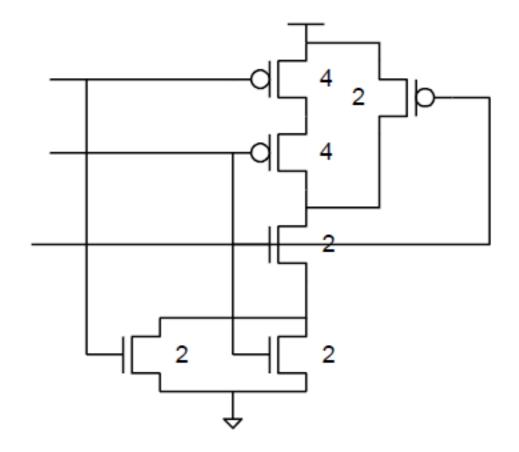
Hint: We want falling and rising times to be equal Also, rising and falling times should match inverter times

$$C_g = C_{g,cons}W$$

$$R = \frac{W}{L} R_{sq}$$

Sizing - Example

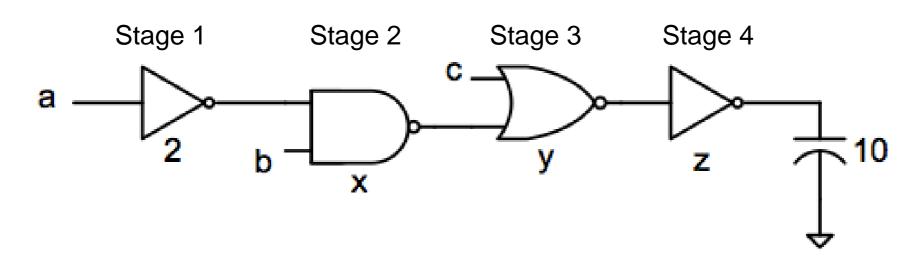




How do we size? Is LE equal for every output?

Hint: We want falling and rising times to be equal Also, rising and falling times should match inverter times

Optimizing Path Delay Example



Stage	1	2	3	4	
LE	1	4/3	5/3	1	$LE_{path} = 2.2$
Fanout	x/2	y/x	z/y	10/z	$f_{eff} = 1.8$
Size	2	3.6	4.86	5.25	

$$SE = f_{eff}$$

$$LE_{j} \frac{C_{j+1}}{C_{j}} = f_{eff}$$

$$\frac{x}{2} \cdot 1 = 1.8$$

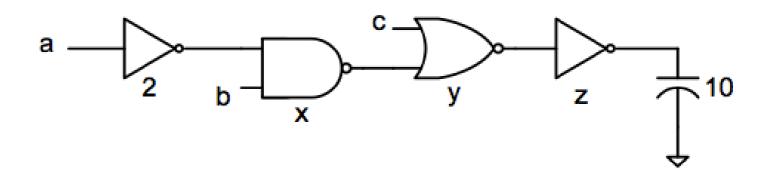
$$\frac{y}{x} \cdot \frac{4}{3} = 1.8$$

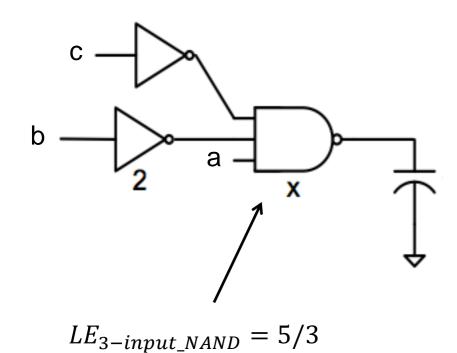
. . .

Change Topology so effective fanout is closer to 4

$$f = a + \bar{b}a = \overline{c + b + \bar{a}}$$

$$f = \overline{(c + b)} \cdot a = \overline{c}\overline{b}a$$





$$LE_{path} = 1 * \frac{5}{3} = 1.66$$

$$f_{eff} = \sqrt{1.66 * \frac{10}{2}} = 2.88$$
Better!

Review: To Size a Path

1. Find Effective Fanout

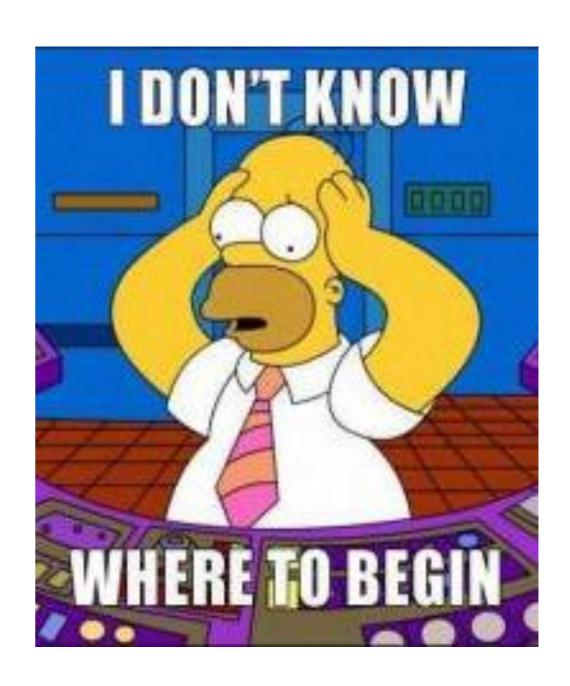
$$f_{eff} = \sqrt[N]{\frac{C_{in,N}}{C_{in,1}} \prod_{j=1}^{N} LE_j} = \sqrt[N]{f_{path}}$$

2. Estimate optimal number of stages. We want f_{eff} to be close to 4 at optimum

$$\widehat{f_{eff}} = 4 = \sqrt[\widehat{N}]{f_{path}} \Leftrightarrow \widehat{N} = log_4(f_{path})$$

- 3. Re-implement using \widehat{N} stages. Re-calculate LE_{path} and f_{eff}
- 4. Calculate sizes, start from either end

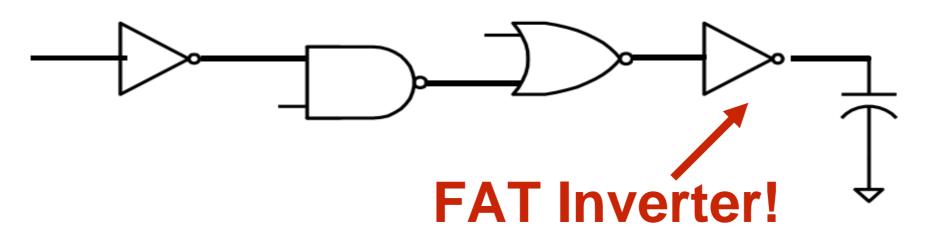
$$LE_{j}\frac{C_{in,j+1}}{C_{in,j}} = f_{eff}$$



LE Energy Considerations

$$-\frac{\frac{\partial E}{\partial W_{i}}}{\frac{\partial D}{\partial W_{i}}} = -\frac{\frac{\partial E}{\partial C_{i}}}{\frac{\partial C_{i}}{\partial C_{i}}} \cdot \frac{\frac{\partial C_{i}}{\partial W_{i}}}{\frac{\partial C_{i}}{\partial W_{i}}} = -\frac{\frac{ec_{i}}{C_{i}}}{\tau \cdot \left(\frac{1}{C_{i-1}} - \frac{C_{i+1}}{C_{i}^{2}}\right)} = \frac{ec_{i}}{\tau \cdot (h_{eff_{i}} - h_{eff_{i-1}})}$$

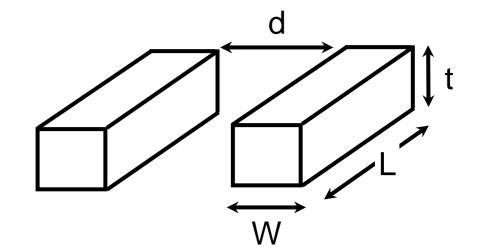
Bigger cells give less performance per energy spent. If we want to <u>equalize marginal cost</u>, then **BIG** cells should have **HIGHER** fanout.



Notes on: The Cost of Wires

Characterized by R & C
 (Oversimplified approximation)

$$R_w = \frac{\rho}{tW} \times L \quad C_w = \frac{\varepsilon t}{d} \times L$$



But propagations follows pi-model

$$\frac{dR}{dC/2} \frac{dR}{dC/2} \frac{dR}{dC/2} \frac{dR}{dC/2} Delay = \frac{1}{2} R_w C_w$$

• R α L, C α L \Rightarrow Delay α L²

Using optimally spaced repeaters we can make it a l

Summary

- Delay is proportional to ln(2)*RC.
- Power can be dynamic (P= a/2 CV^2 x f) and static (Ileak*Vdd).
- C is load + parasitic.
- Optimum chain delay require equalized effective fanout.

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